

TVS Diode Array

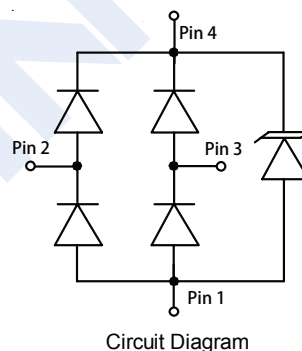
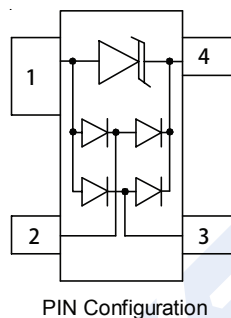
1KE05-4

■ Features

- ESD protection to
 - IEC 61000-4-2 (ESD) $\pm 15\text{kV}$ (air), $\pm 8\text{kV}$ (contact)
 - IEC 61000-4-4 (EFT) 40A (5/50ns)
 - IEC 61000-4-5 (Lightning) 24A (8/20 μs)
- Array of surge rated diodes with internal TVS Diode
- Protects two I/O lines
- Low capacitance (<10pF) for high-speed interfaces
- Low clamping voltage
- Low operating voltage: 5.0V
- Solid-state silicon-avalanche technology
- Marking : SL3

■ Applications

- USB Power & Data Line Protection
- Ethernet 10BaseT
- I²C Bus Protection
- Video Line Protection
- T1/E1 secondary IC Side Protection
- Portable Electronics
- Microcontroller Input Protection
- WAN/LAN Equipment
- ISDN S/T Interface



■ Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
Peak pulse power ($t_p = 8/20\mu\text{s}$)	P_{pk}	500	W
Peak pulse current ($t_p = 8/20\mu\text{s}$)	I_{pp}	25	A
Peak forward voltage ($I_F = 1\text{A}$, $t_p = 8/20\mu\text{s}$)	V_{FP}	1.5	V
Lead soldering temperature	T_L	260 (10 sec.)	°C
Operating temperature	T_J	-55 to +125	
Storage temperature	T_{stg}	-55 to +150	

■ Electrical Characteristics

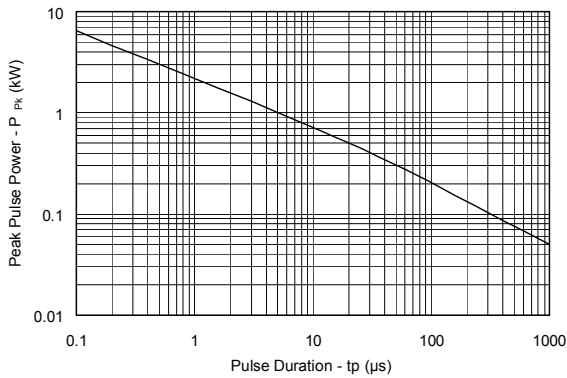
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Reverse stand-off voltage	V_{RWM}				5	V
Reverse breakdown voltage	V_{BR}	$I_R = 1\text{mA}$	6			
Reverse leakage current	I_R	$V_{RWM} = 5\text{V}$, $T = 25^\circ\text{C}$			5	μA
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=1\text{A}$			9.8	V
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=10\text{A}$			12	
Clamping voltage ($t_p=8/20\mu\text{s}$)	V_C	$I_{PP}=25\text{A}$			20	
Junction capacitance	C_J	$V_R = 0\text{Vdc}$, $f=1\text{MHz}$ Between I/O pins and GND		6	10	pF
		$V_R = 0\text{Vdc}$, $f=1\text{MHz}$ Between I/O pins		3		

TVS Diode Array

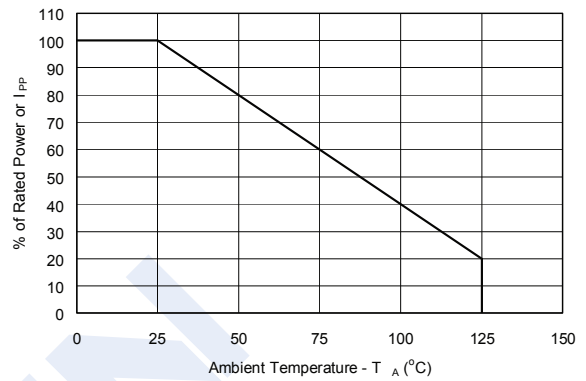
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Typical Characteristics

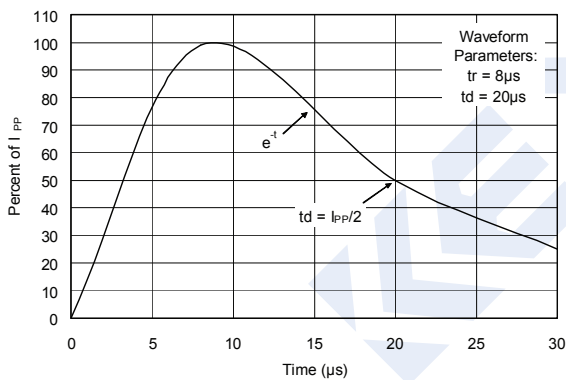
Non-Repetitive Peak Pulse Power vs. Pulse Time



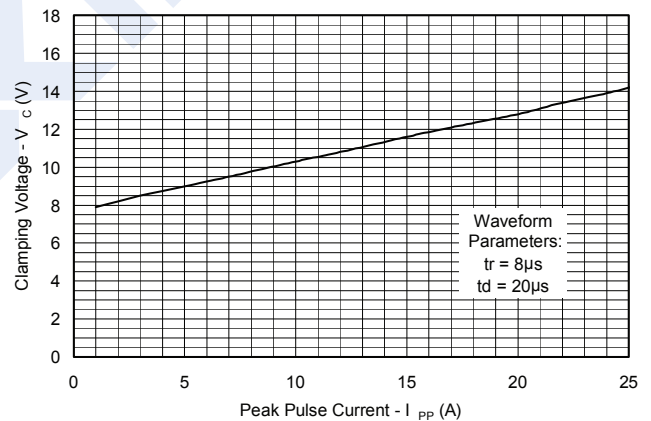
Power Derating Curve



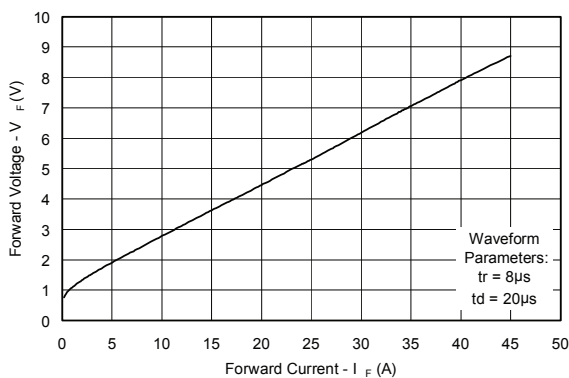
Pulse Waveform



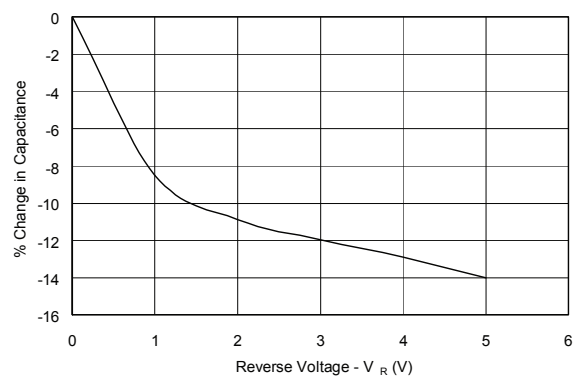
Clamping Voltage vs. Peak Pulse Current



Forward Voltage vs. Forward Current



Capacitance vs. Reverse Voltage



TVS Diode Array

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■ Applications Information

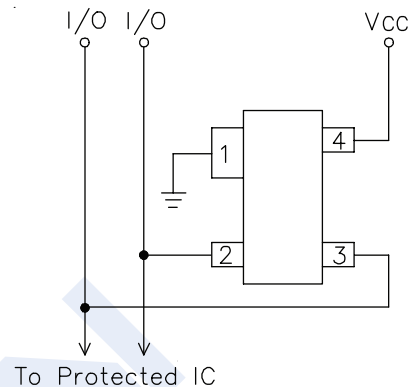
Device Connection Options for Protection of Two High-Speed Data Lines

The 1KE05-4 TVS is designed to protect two data lines from transient over-voltages by clamping them to a fixed reference. When the voltage on the protected line exceeds the reference voltage (plus diode V_F) the steering diodes are forward biased, conducting the transient current away from the sensitive circuitry. Data lines are connected at pins 2 and 3. The negative reference (REF1) is connected at pin 1. This pin should be connected directly to a ground plane on the board for best results. The path length is kept as short as possible to minimize parasitic inductance. The positive reference (REF2) is connected at pin 4. The options for connecting the positive reference are as follows:

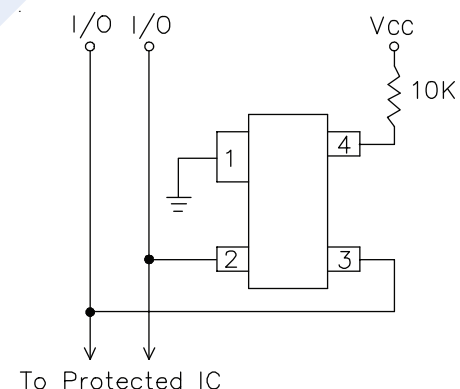
1. To protect data lines and the power line, connect pin 4 directly to the positive supply rail (V_{CC}). In this configuration the data lines are referenced to the supply voltage. The internal TVS diode prevents over-voltage on the supply rail.
2. The 1KE05-4 can be isolated from the power supply by adding a series resistor between pin 4 and V_{CC} . A value of 10k is recommended. The internal TVS and steering diodes remain biased, providing the advantage of lower capacitance.
3. In applications where no positive supply reference is available, or complete supply isolation is desired, the internal TVS may be used as the reference. In this case, pin 4 is not connected. The steering diodes will begin to conduct when the voltage on the protected line exceeds the working voltage of the TVS (plus one diode drop).

ESD Protection With 1KE05-4

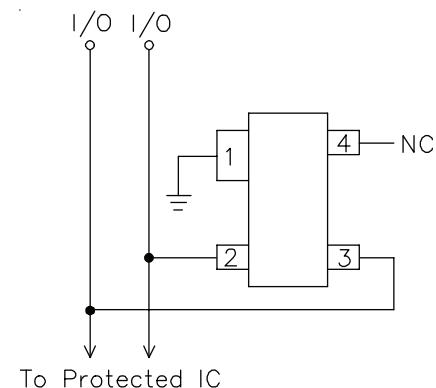
1KE05-4 are optimized for ESD protection using the rail-to-rail topology. Along with good board layout, these devices virtually eliminate the disadvantages of using discrete components to implement this topology. Consider the situation shown in Figure 1 where discrete diodes or diode arrays are configured for rail-to-rail protection on a high speed line. During positive duration ESD events, the top diode will be forward biased when the voltage on the protected line exceeds the reference voltage plus the V_F drop of the diode.

Data Line and Power Supply Protection Using V_{CC} as reference

Data Line Protection with Bias and Power Supply Isolation Resistor



Data Line Protection Using Internal TVS Diode as Reference



TVS Diode Array

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■ Applications Information (continued)

For negative events, the bottom diode will be biased when the voltage exceeds the V_F of the diode. At first approximation, the clamping voltage due to the characteristics of the protection diodes is given by:

$$\begin{aligned} V_C &= V_{CC} + V_F & (\text{for positive duration pulses}) \\ V_C &= -V_F & (\text{for negative duration pulses}) \end{aligned}$$

However, for fast rise time transient events, the effects of parasitic inductance must also be considered as shown in Figure 2. Therefore, the actual clamping voltage seen by the protected circuit will be:

$$\begin{aligned} V_C &= V_{CC} + V_F + L_P di_{ESD}/dt & (\text{for positive duration pulses}) \\ V_C &= -V_F - L_G di_{ESD}/dt & (\text{for negative duration pulses}) \end{aligned}$$

ESD current reaches a peak amplitude of 30A in 1ns for a level 4 ESD contact discharge per IEC 61000-4-2. Therefore, the voltage overshoot due to 1nH of series inductance is:

$$V = L_P di_{ESD}/dt = 1 \times 10^{-9} (30 / 1 \times 10^{-9}) = 30V$$

Example:

Consider a $V_{CC} = 5V$, a typical V_F of 30V (at 30A) for the steering diode and a series trace inductance of 10nH. The clamping voltage seen by the protected IC for a positive 8kV (30A) ESD pulse will be:

$$V_C = 5V + 30V + (10nH \times 30V/nH) = 335V$$

This does not take into account that the ESD current is directed into the supply rail, potentially damaging any components that are attached to that rail. Also note that it is not uncommon for the V_F of discrete diodes to exceed the damage threshold of the protected IC. This is due to the relatively small junction area of typical discrete components. It is also possible that the power dissipation capability of the discrete diode will be exceeded, thus destroying the device.

The 1KE05-4 is designed to overcome the inherent disadvantages of using discrete signal diodes for ESD suppression. The 1KE05-4's integrated TVS diode helps to mitigate the effects of parasitic inductance in

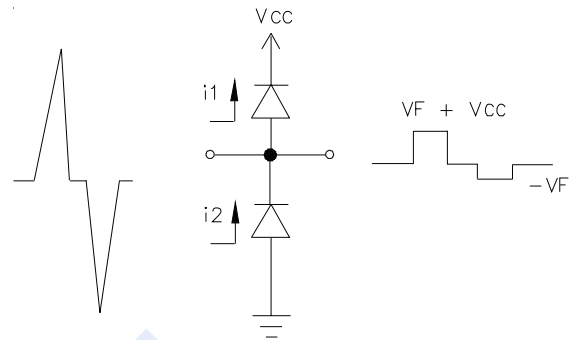


Figure 1 - "Rail-To-Rail" Protection Topology (First Approximation)

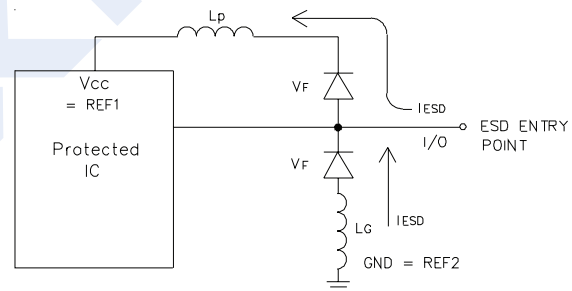


Figure 2 - The Effects of Parasitic Inductance When Using Discrete Components to Implement Rail-To-Rail Protection

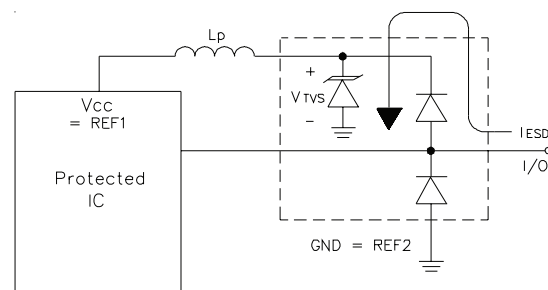


Figure 3 - Rail-To-Rail Protection Using TVS Arrays

TVS Diode Array

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■ Applications Information (continued)

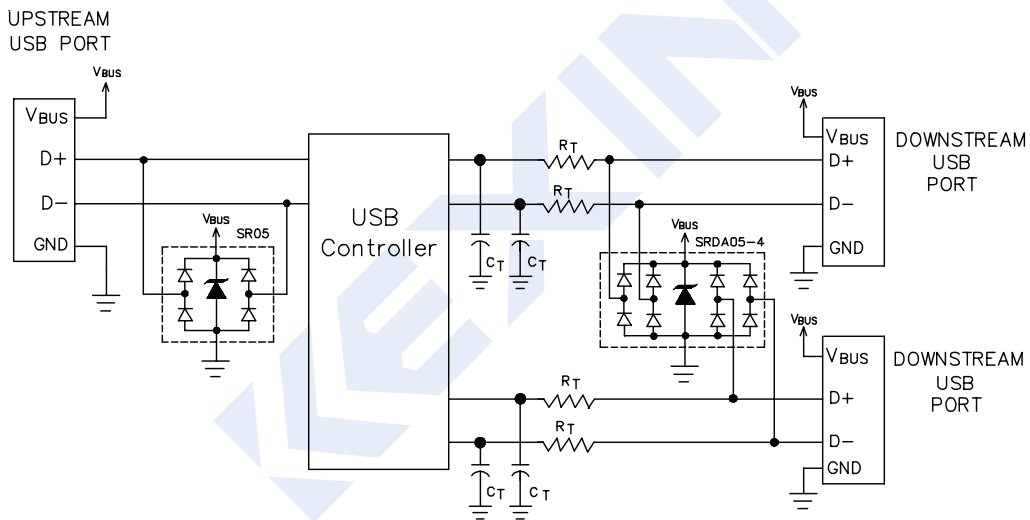
the power supply connection. During an ESD event, the current will be directed through the integrated TVS diode to ground. The total clamping voltage seen by the protected IC due to this path will be:

$$V_C = V_{F(Clamp)} + V_{TVS}$$

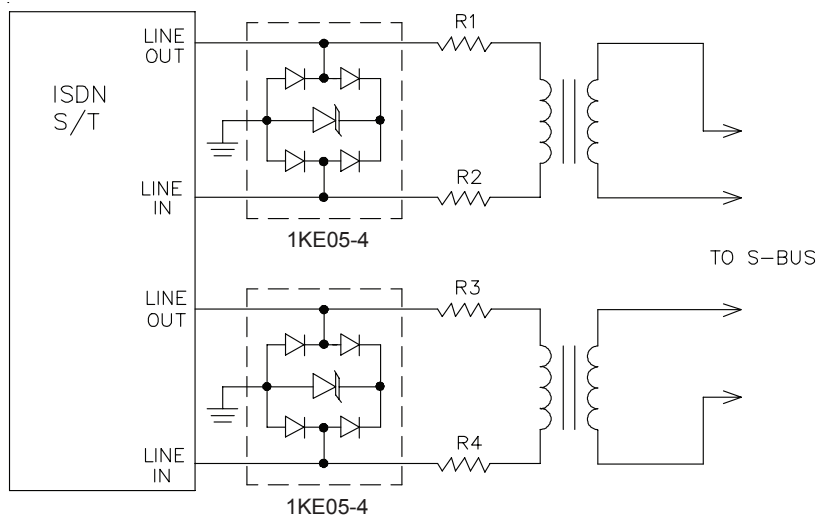
This is given in the data sheet as the rated clamping voltage of the device. For a 1KE05-4 the typical clamping voltage is <16V at $I_{pp}=30A$. The diodes internal to the 1KE05-4 are low capacitance, fast switching that are rated to handle transient currents and maintain excellent forward voltage characteristics.

Universal Serial Bus ESD Protection

The figure below illustrates how to use the 1KE05-4 to protect one upstream USB port and the 1KE05-4 to protect two downstream USB ports. When the voltage on the data lines exceed the bus voltage (plus one diode drop), the internal rectifiers are forward biased conducting the transient current away from the protected controller chip. The TVS diode directs the surge to ground. The TVS diode also acts to suppress ESD strikes directly on the voltage bus. Thus, both power and data pins are protected with a single device.



Universal Serial Bus ESD Protection



ISDN S/T Interface Protection

TVS Diode Array

1KE05-4

■ Package Outline Dimensions

SOT-143

Symbol	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.79	3.04	0.110	0.120
B	1.90		0.075	
C	0.76	0.93	0.030	0.037
D	0.36	0.50	0.014	0.020
E	1.19	1.40	0.047	0.055
F	-	2.50	-	0.098
G	1.70		0.067	
H	0.15	-	0.006	-
J	0.08	0.15	0.003	0.006
K	-	0.13	-	0.005
L	-	1.14	-	0.045

Recommended Soldering Pad Layout